

# FRAUNHOFER INSTITUTE FOR INTEGRATED SYSTEMS AND DEVICE TECHNOLOGY IISB

MNE 2015, 41<sup>st</sup> International Conference on Micro and Nano Engineering, The Hague, The Netherlands

# Defined area polymer working stamp manufacture for S&R UV-NIL by direct laser writing

M. Rumler<sup>a, c</sup>, F. Michel<sup>b</sup>, M. Becker<sup>d</sup>, L. Baier<sup>a</sup>, M. Förthner<sup>b,c</sup>, M. Rommel<sup>a</sup>, A. Schleunitz<sup>e</sup>, J. Klein<sup>e</sup>

<sup>a</sup> Fraunhofer Institute for Integrated Systems and Device Technology (IISB), 91058 Erlangen, Germany

<sup>b</sup> Chair of Electron Devices, University Erlangen-Nuremberg, 91058 Erlangen, Germany

IISB

<sup>c</sup> Erlangen Graduate School in Advanced Optical Technologies (SAOT), 91058 Erlangen, Germany

<sup>d</sup> NanoWorld Services GmbH, Erlangen, 91058, Germany

<sup>e</sup> micro resist technology GmbH, Berlin, 12555, Germany

#### Introduction

- Hybrid polymer working stamps for UV-NIL have become a common alternative to quartz molds [1-3]
- Defined area working stamps are of great interest for e.g. seamless step & repeat

Challenges

Identification of process window for DLW on hybrid polymers [4]  $\rightarrow$  First exposure experiments in air, curing feasible?

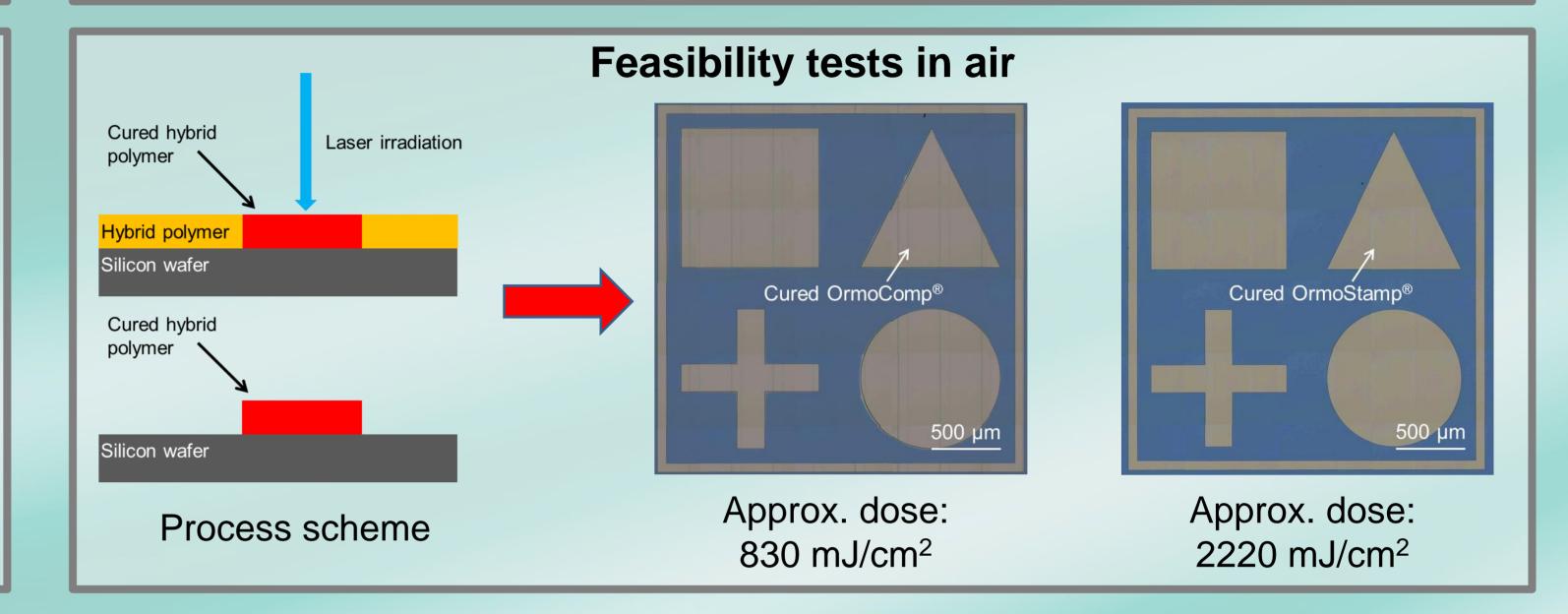
#### UV-NIL [3]

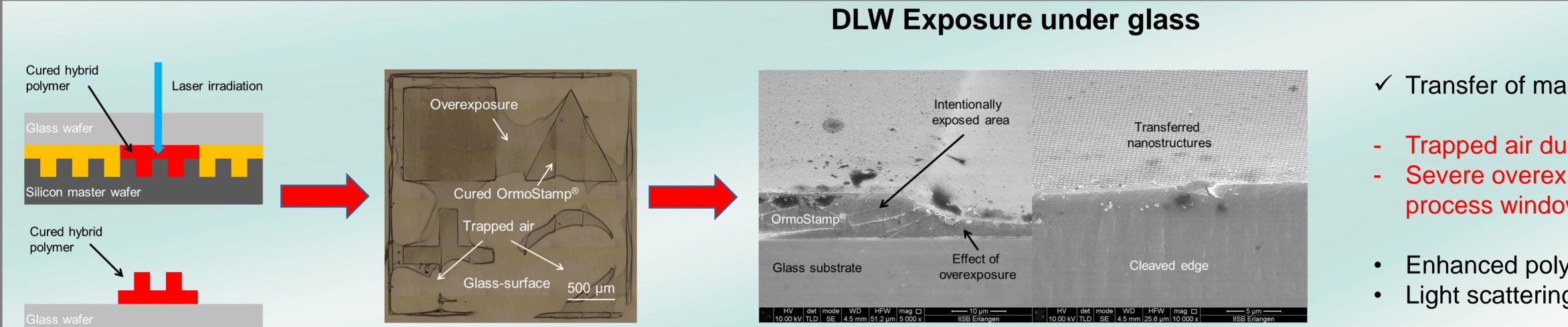
Direct Laser Writing (DLW) could be an interesting option for the fabrication of the intended hybrid polymer molds (freedom of design, no mask needed)

# **Experimental setup**

- Spin-coating of hybrid polymers OrmoStamp<sup>®</sup> and OrmoComp<sup>®</sup> @5000 rpm for 30 s
- Exposure @405 nm using Heidelberg DWL66+
- Development in OrmoDev for 2 min @RT
- Characterization using optical microscope, AFM and SEM

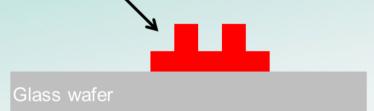
- Fabrication of defined mesa-structures (sufficient height, steep sidewalls)
- Faithful replication of master structures into hybrid polymer

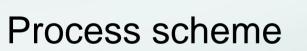


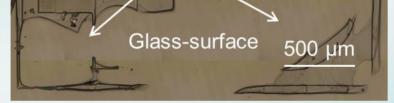


✓ Transfer of master structures successful

- Trapped air due to non-conformal contact
- Severe overexposure due to shift in process window compared to exposure in air







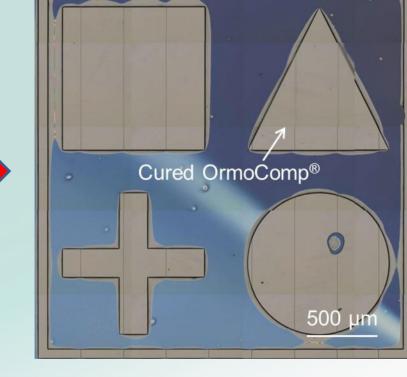
Approx. dose: 665 mJ/cm<sup>2</sup>

SEM cross section showing widening of OrmoStamp<sup>®</sup> mesa structure

# **DLW Exposure under PDMS mold**

Cured hybrid Laser irradiation polymer PDMS mold Silicon wafer Cured hybrid polymer Silicon wafer

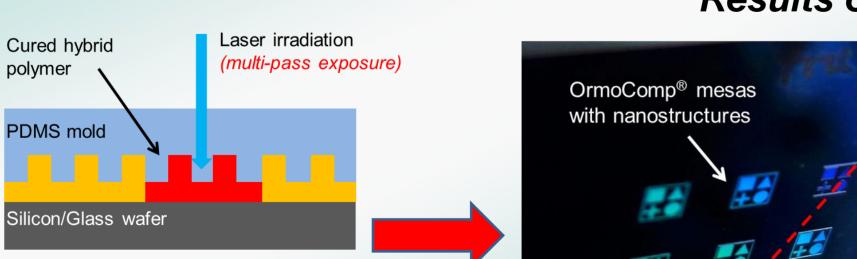
**Process scheme** 



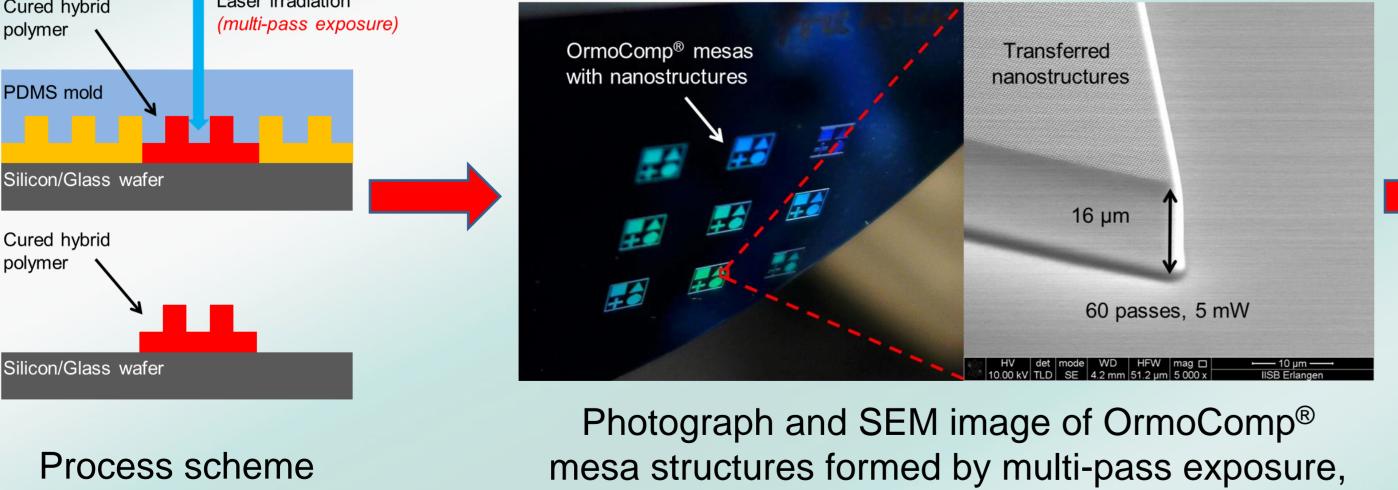
Approx. dose: 665 mJ/cm<sup>2</sup>

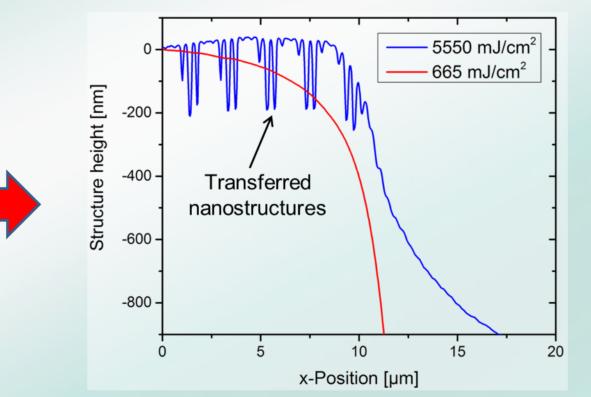


Approx. dose: 5550 mJ/cm<sup>2</sup>



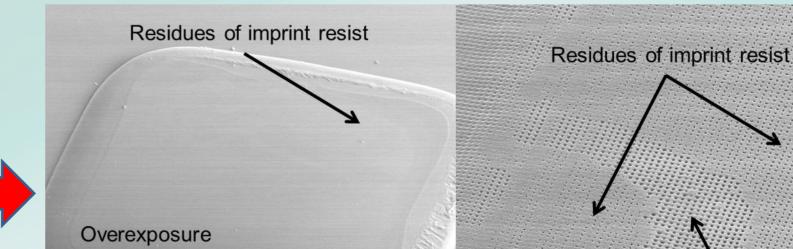
#### Results on silicon substrate





Mesa edges formed by approx. doses of 665 and 5550 mJ/cm<sup>2</sup>

#### **Results on glass substrate**



- Enhanced polymerization due to oxygen exclusion?
- Light scattering by master structures?



#### Use of PDMS-mold as master

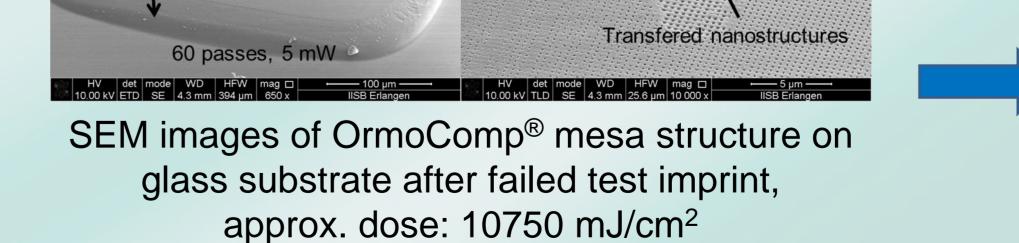
- Transfer of master structures successful Less air traps  $\checkmark$
- Problems with overexposure remain
- Influence of heat transfer?



# Multi-pass exposure

- ✓ Vertical sidewalls on Si substrate
- Slight overexposure on glass substrate
- Test imprint failed due to ASL

approx. dose: 10750 mJ/cm<sup>2</sup>



#### problem

Further experiments on glass necessary

### Conclusions

Successful fabrication of hybrid polymer mesas containing nanostructures by DLW Multi-pass exposure with reduced laser power leads to vertical sidewall formation

# Outlook

Investigate influence of post exposure bake (decrease of UV dose possible?) Identify tolerable sidewall angle for S&R mesa structures (decrease of process time)

[1] A. Kuklowska et al., Microelectron. Eng. 4-6 (2009), 697. [2] M. Mühlberger et al., Microelectron. Eng. 4-6 (2009), 691. [3] A. Schleunitz et al., J. Vac. Sci. Technol. B 28 (2010) C6M37. [4] A. Singh et al., Micromachines 5 (2014), 472.

Fraunhofer Institute for Integrated Systems and Device Technology Schottkystraße 10

91058 Erlangen, Germany

maximilian.rumler@iisb.fraunhofer.de Mail:

http://www.iisb.fraunhofer.de Internet:







